

**Glass Passivated Bridge Rectifiers****Reverse Voltage - 50 to 1000 Volts****Forward Current - 4.0 Amperes****Features**

- Glass passivated chip
- Low forward voltage drop
- Ideal for printed circuit board
- High surge current capability
- Meet UL flammability classification 94V-0

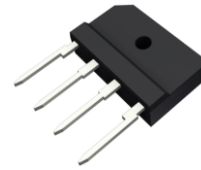
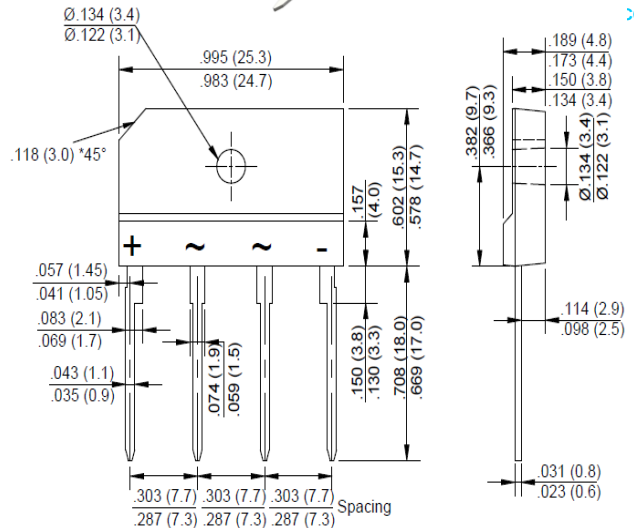
Mechanical Data

- Polarity: Symbol marked on body
- Mounting position: Any

Note: Products with logo  or  are made by HY Electronic (Cayman) Limited.

Applications

- General purpose use in AC/DC bridge full wave rectification, for SMPS, lighting ballaster, adapter, etc.

4GBJ**RoHS**
COMPLIANT**Maximum Ratings and Electrical Characteristics**

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristics	Symbol	4GBJ	4GBJ	4GBJ	4GBJ	4GBJ	4GBJ	4GBJ	Unit
		4005	401	402	404	406	408	410	
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current (with heatsink Note 2) @ TC=100℃ (without heatsink)	I _(AV)	4.0							A
		2.4							
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave, Superimposed on Rated Load (JEDEC Method)	I _{FSM}	135							A
I ² t Rating for Fusing (t<8.3mS)	I ² t	75.6							A ² s
Peak Forward Voltage Per Diode at 2A DC	V _F	0.95							V
Peak Forward Voltage per Diode at 4A DC	V _F	1.05							V
Maximum DC Reverse Current at Rated @T _J =25℃	I _R	5							μA
DC Blocking Voltage per Diode @T _J =125℃		500							
Typical Junction Capacitance per Diode (Note1)	C _J	45							pF
Typical Thermal Resistance to case (with heatsink (Note2))	R _{θJC}	2.2							℃/W
Operating Junction Temperature Range	T _J	-55 to +150							℃
Storage Temperature Range	T _{STG}	-55 to +150							℃

Notes: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

2. Device mounted on 50mm*50mm*1.6mm Cu plate heatsink.

3. The typical data above is for reference only



Fig. 1 - Forward Current Derating Curve

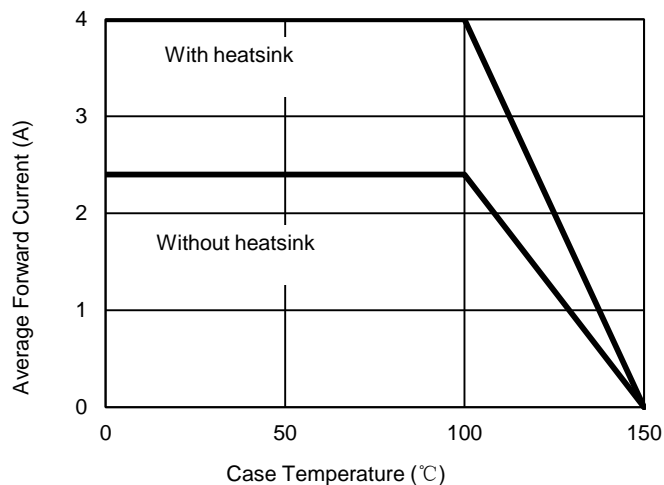


Fig. 2 - Maximum Non-Repetitive Surge Current

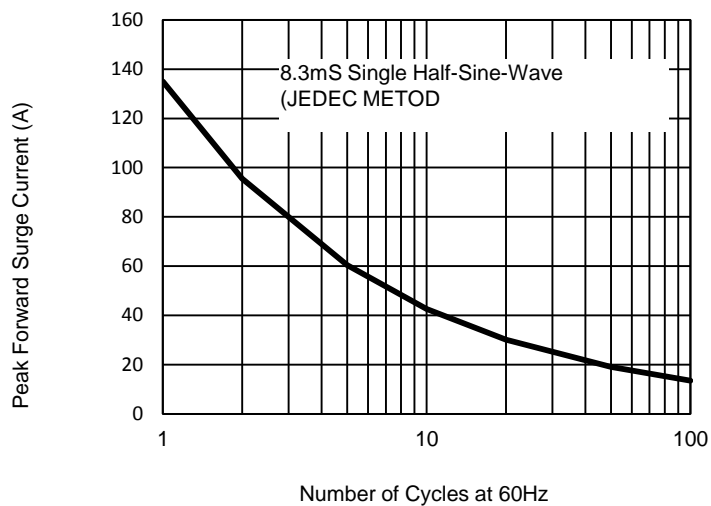


Fig. 3 - Typical Reverse Characteristics

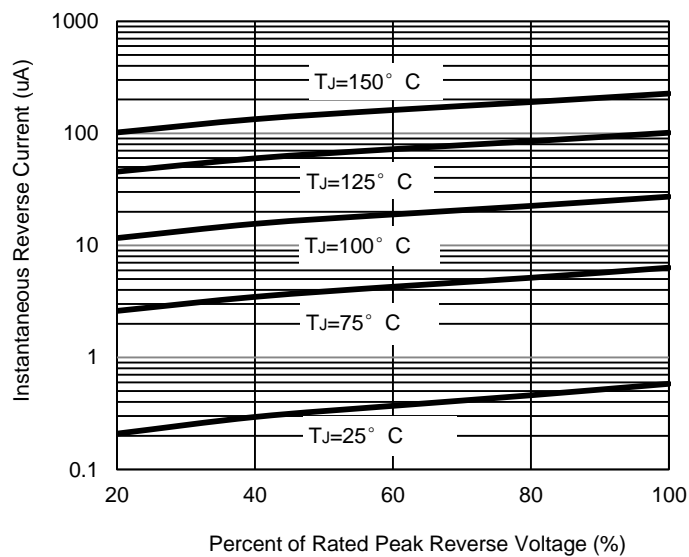


Fig. 4 - Typical Forward Characteristics

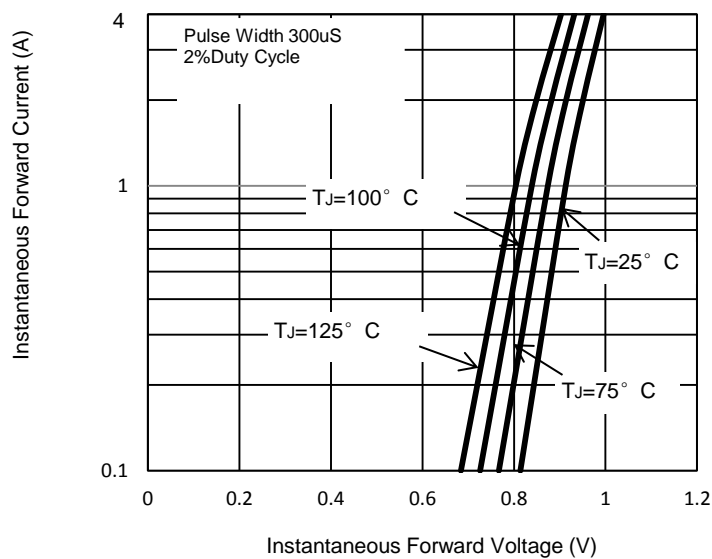
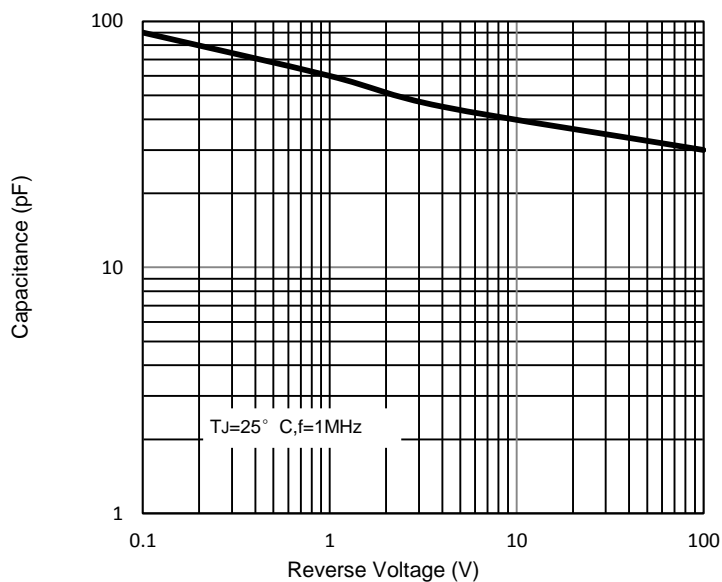


Fig. 5 - Typical Junction Capacitance





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